



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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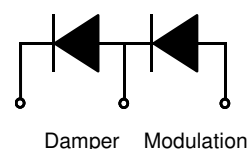
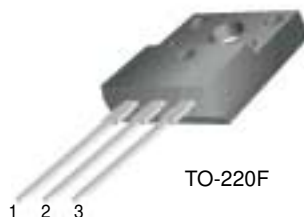
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



FFPF60B150DS

Features

- High voltage and high reliability
- High speed switching
Modulation diode / Damper diode
- Low conduction loss
Modulation diode / Damper diode



Applications

- (Modulation + Damper) diode designed for horizontal deflection circuits in C-TVs & monitors

DAMPER + MODULATION DIODE

Absolute Maximum Ratings (Modulation) $T_C=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Value	Units
V_{RRM}	Peak Repetitive Reverse Voltage	600	V
$I_{F(AV)}$	Average Rectified Forward Current @ $T_C = 100^\circ\text{C}$	20	A
I_{FSM}	Non-repetitive Peak Surge Current 60Hz Single Half-Sine Wave	120	A
T_J, T_{STG}	Operating Junction and Storage Temperature	- 65 to +150	$^\circ\text{C}$

Absolute Maximum Ratings (Damper) $T_C=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Value	Units
V_{RRM}	Peak Repetitive Reverse Voltage	1500	V
$I_{F(AV)}$	Average Rectified Forward Current @ $T_C = 100^\circ\text{C}$	6	A
I_{FSM}	Non-repetitive Peak Surge Current 60Hz Single Half-Sine Wave	60	A
T_J, T_{STG}	Operating Junction and Storage Temperature	- 65 to +150	$^\circ\text{C}$

Thermal Characteristics

Symbol	Parameter	Value	Units
$R_{\theta JC}$	Maximum Thermal Resistance, Junction to Case	3.3	$^\circ\text{C/W}$

Electrical Characteristics*(Modulation) $T_C=25\text{ }^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Min.	Typ.	Max.	Units
V_{FM}	Maximum Instantaneous Forward Voltage $I_F = 20\text{A}$ $I_F = 20\text{A}$			$T_C = 25\text{ }^\circ\text{C}$	2.2
				$T_C = 100\text{ }^\circ\text{C}$	2.0
I_{RM}	Maximum Instantaneous Reverse Current @ rated V_R				μA
				$T_C = 25\text{ }^\circ\text{C}$	10
				$T_C = 100\text{ }^\circ\text{C}$	100
t_{rr}	Maximum Reverse Recovery Time				90 ns
I_{rr}	Maximum Reverse Recovery Current				8 A
Q_{rr}	Maximum Reverse Recovery Charge ($I_F = 20\text{A}$, $di/dt = 200\text{A}/\mu\text{s}$)				360 nC

* Pulse Test: Pulse Width=300 μs , Duty Cycle=2%**Electrical Characteristics*(Damper) $T_C=25\text{ }^\circ\text{C}$ unless otherwise noted**

Symbol	Parameter	Min	Typ	Max	Units
V_{FM}	Maximum Instantaneous Forward Voltage $I_F = 6\text{A}$ $I_F = 6\text{A}$			$T_C = 25\text{ }^\circ\text{C}$	1.6
				$T_C = 100\text{ }^\circ\text{C}$	1.4
I_{RM}	Maximum Instantaneous Reverse Current @ rated V_R				μA
				$T_C = 25\text{ }^\circ\text{C}$	7
				$T_C = 100\text{ }^\circ\text{C}$	60
t_{rr}	Maximum Reverse Recovery Time ($I_F = 1.0\text{A}$, $di/dt = 50\text{A}/\mu\text{s}$)				170 ns
t_{fr}	Maximum Forward Recovery Time ($I_F = 6.5\text{A}$, $di/dt = 50\text{A}/\mu\text{s}$)				350 ns
V_{FRM}	Maximum Forward Recovery Voltage				17 V

* Pulse Test: Pulse Width=300 μs , Duty Cycle=2%

Typical Characteristics

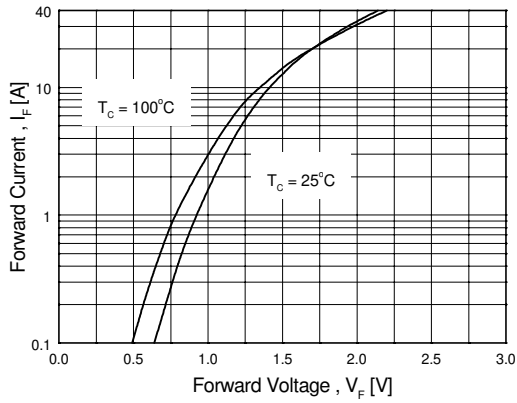


Figure 1. Typical Forward Characteristics (Modulation Diode)

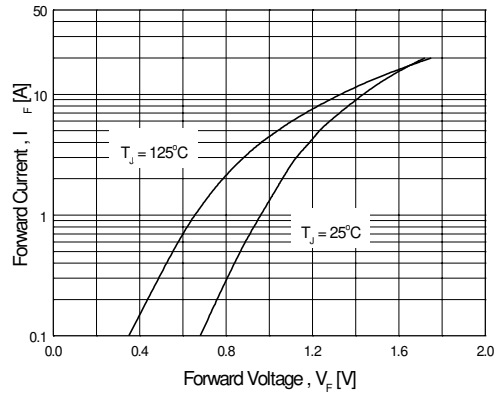


Figure 2. Typical Forward Characteristics (Damper Diode)

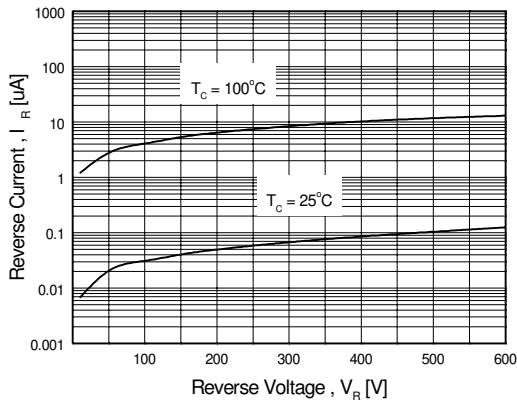


Figure 3. Typical Reverse Current vs. Reverse Voltage (Modulation Diode)

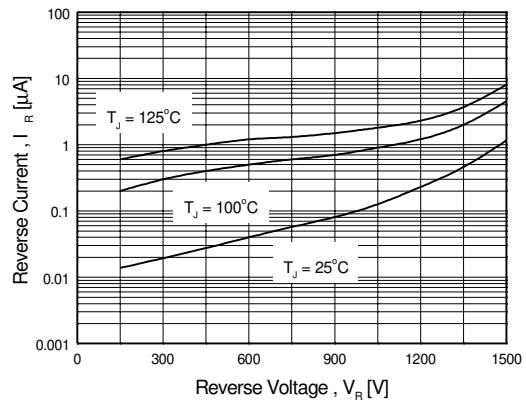


Figure 4. Typical Reverse Current vs. Reverse Voltage (Damper Diode)

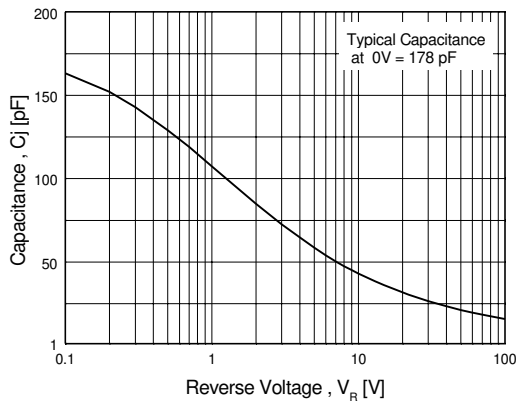


Figure 5. Typical Junction Capacitance (Modulation Diode)

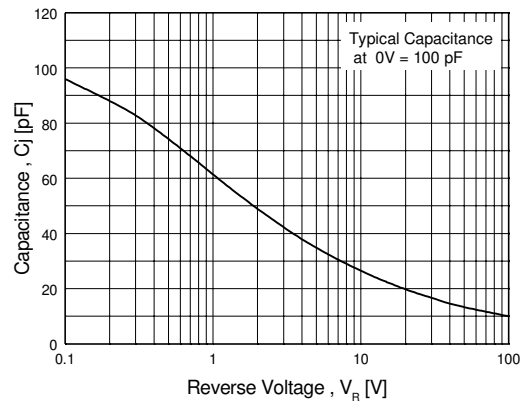


Figure 6. Typical Junction Capacitance (Damper Diode)

Typical Characteristics

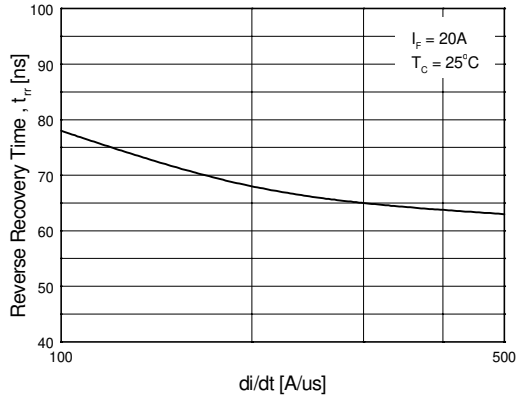


Figure 7. Typical Reverse Recovery Time vs. di/dt (Modulation Diode)

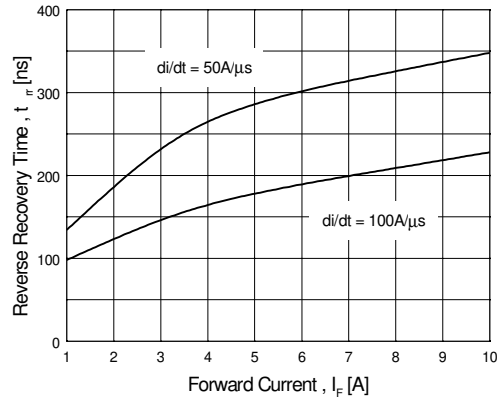


Figure 8. Typical Reverse Recovery Time vs. di/dt (Damper Diode)

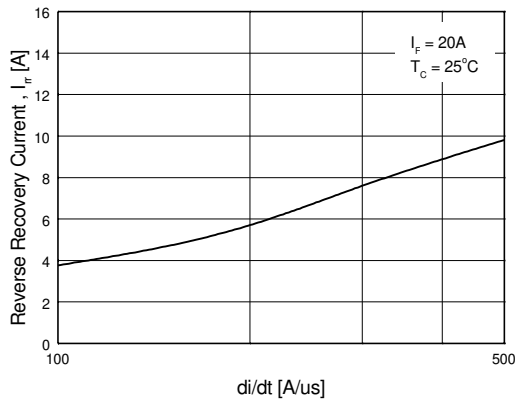


Figure 9. Typical Reverse Recovery Current vs. di/dt (Modulation Diode)

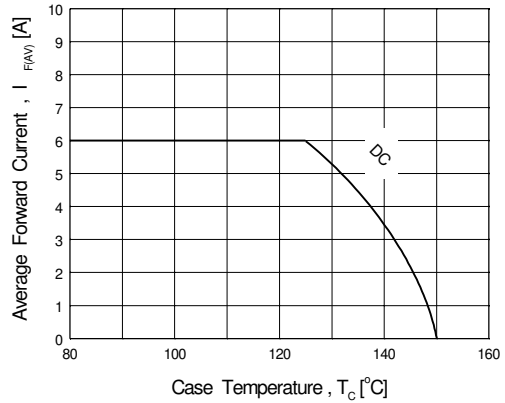


Figure 10. Forward Current Derating Curve (Damper Diode)

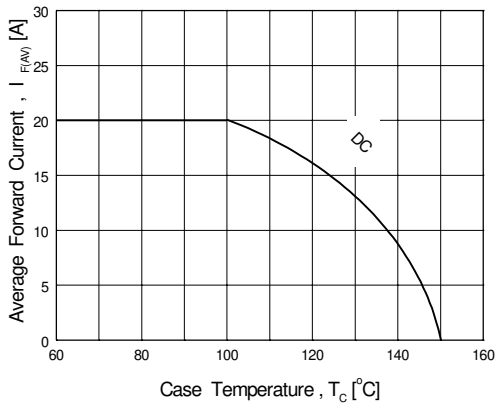
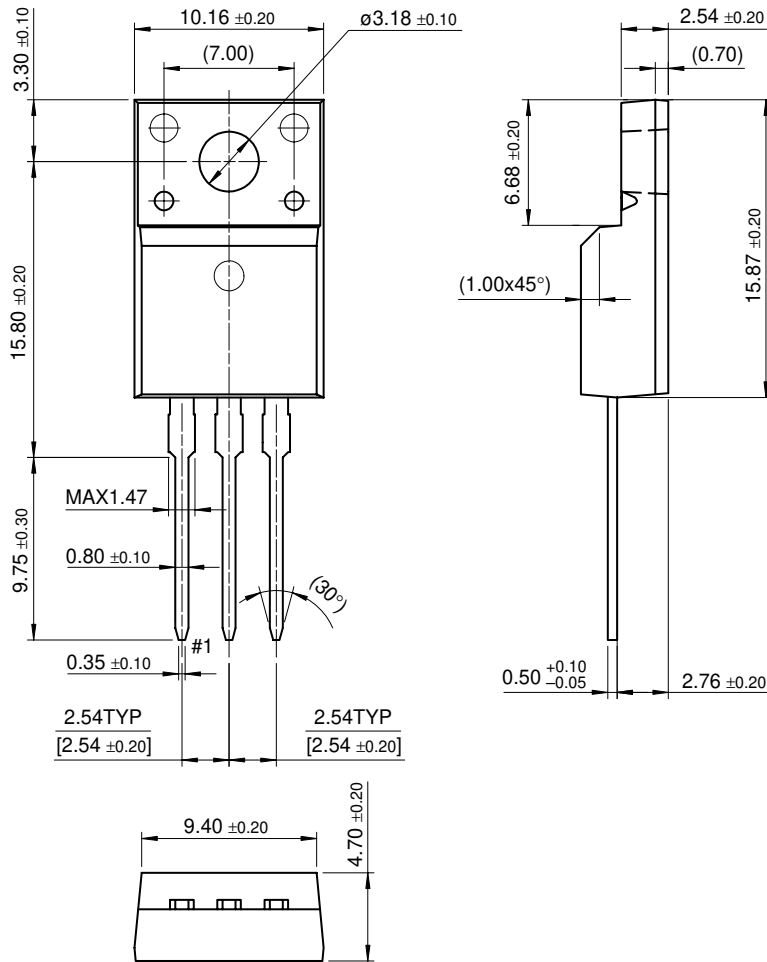


Figure 11. Forward Current Derating Curve (Modulation Diode)

Package Dimensions

TO-220F

FFPF60B150DS



Dimensions in Millimeters

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CoolFET™	GlobalOptoisolator™	PowerTrench [®]	SuperSOT™-8
CROSSVOLT™	GTO™	QFET™	SyncFET™
DenseTrench™	HiSeC™	QS™	TinyLogic™
DOME™	ISOPLANAR™	QT Optoelectronics™	UHC™
EcoSPARK™	LittleFET™	Quiet Series™	UltraFET [®]
E ² CMOS™	MicroFET™	SLIENT SWITCHER [®]	VCX™
EnSigna™	MICROWIRE™	SMART START™	
FACT™	OPTOLOGIC™	Star* Power™	
FACT Quiet Series™	OPTOPLANAR™	Stealth™	

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